Final Product Change Notification

201707008F01

Issue Date: 20-Jul-2017
Effective Date: 18-Oct-2017

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

Change Category

[ ] Wafer Fab Process
[ ] Wafer Fab Materials
[ ] Wafer Fab Location
[ ] Assembly Process
[X] Assembly Materials
[ ] Assembly Location
[ ] Product Marking
[ ] Mechanical Specification
[ ] Packing/Shipping/Labeling
[ ] Test Location
[ ]Test Process
[ ] Test Equipment
[ ] Design
[ ] Errata
[ ] Electrical spec./Test coverage

SGTL5000 Copper Wire Qualification

Details of this Change

NXP Semiconductors announces the addition of Palladium Copper (PdCu) wire as a wirebond material for the SGTL5000XNAA3/R2 QFN-EP 32 5x5 package devices. These products are now qualified for assembly at ASECL, Taiwan assembly site. These products were previously assembled with Gold (Au) wire at ASECL, Taiwan assembly site.

NXP Semiconductors also announces the addition of Palladium Copper (PdCu) wire as a wirebond material along with Sumitomo EME-G700LA mold compound and Henkel ATB-125 die attach material for the SGTL5000XNLA3/R2 QFN-EP 20 3x3 package devices. These products are now qualified for assembly at ASECL, Taiwan assembly site. These products were previously assembled with Gold (Au) wire, Hitachi CEL9240HF10AK mold compound, and Nitto 550 die attach material at ASECL, Taiwan assembly site.

Why do we Implement this Change

The transfer from Gold to Palladium Copper wire is required to mitigate against raw material cost increases and for supply assurance. The change to mold compound and die attach material for QFN-EP 20 3x3 package is required to standardize the bill of materials for ASECL QFN package current production.

Identification of Affected Products

Product identification does not change

There is no change to orderable part number. The tracecode marking on the device includes assembly site and datecode. NXP will have traceability by assembly site and datecode.

Product Availability

Sample Information
Samples are available from 21-Jul-2017
Samples available for SGTL5000XNAA3 and SGTL5000XNLA3 with special marking for customer evaluation.
Production
Planned first shipment 19-Oct-2017

Impact

No change to form, fit, or function. Reliability is equivalent or improved.
Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 19-Aug-2017.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Name	Status	Product Line
SGTL5000XNAA3	935310058557	SGTL5000XNAA3	Audio Codex	HVQFN32	RFS	BL Advanced Automotive Analog
SGTL5000XNLA3R2	935314076518	SGTL5000XNLA3R2	Audio Codex	HUQFN20	RFS	BL Advanced Automotive Analog
SGTL5000XNAA3R2	935310058518	SGTL5000XNAA3R2	Audio Codex	HVQFN32	RFS	BL Advanced Automotive Analog
SGTL5000XNLA3	935314076557	SGTL5000XNLA3	Audio Codex	HUQFN20	RFS	BL Advanced Automotive Analog